

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|---|---|------------------|---------|------------------|
| S88 | 0 | "chip-on-chip" same (project\$6) near15 inactive | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:46 |
| S87 | 0 | "chip-on-chip" same (project\$6) near15 height | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:46 |
| S86 | 58141 | chip near2 chip or "chip-on-chip" same (project\$6) near15 height | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:46 |
| S85 | 58141 | chip near2 chip or "chip-on-chip" same (project\$6) near15 inactive | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:46 |
| S92 | 0 | chip\$3chip same (project\$6) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:47 |
| S91 | 0 | chip near2 "on" near2 chip same (project\$6) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:47 |
| S90 | 0 | "chip on chip" same (project\$6) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:47 |
| S89 | 0 | "chip on chip" same (project\$6) near15 inactive | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:47 |
| S95 | 4 | chip\$5chip same electrode near5 height | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:49 |
| S93 | 47 | chip\$5chip same (project\$6) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/20 14:49 |

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|-----|-----|---|---|----|----|------------------|
| S84 | 7 | kazutaka near2 shibata.in. and chip\$1on\$1chip same resin and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| S56 | 46 | (Kazutaka near2 Shibata).in. and chip\$1on\$1chip | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| S16 | 30 | semiconductor near3 chip same resin same electrode same (polish\$ or grind\$) same (rear or back) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| S8 | 176 | resin near10 (back or back\$1sid\$) same (polish\$ or grind\$) and semiconduct\$ | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| S7 | 453 | (resin same (polish\$ or grind\$)) same (back or back\$1sid\$) and semiconduct\$ | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| L5 | 46 | semiconductor near3 chip same resin same electrode same (polish\$ or grind\$) same (rear or back) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| L4 | 716 | (resin same (polish\$ or grind\$)) same (back or back\$1sid\$) and semiconduct\$ | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| L3 | 276 | resin near10 (back or back\$1sid\$) same (polish\$ or grind\$) and semiconduct\$ | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| L2 | 7 | kazutaka near2 shibata.in. and chip\$1on\$1chip same resin and wafer | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |
| L1 | 55 | (Kazutaka near2 Shibata).in. and chip\$1on\$1chip | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:12 |

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|-----|-----|----------------------------|---|----|----|------------------|
| S94 | 117 | chip\$5chip same electrode | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:13 |
| L6 | 117 | chip\$5chip same electrode | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/21 18:13 |